## Panasonic Industrial Devices Materials Europe GmbH **Specification Sheet**

IPC-4101D/127 Specifiction sheet # Reinforcement: 1: Woven E-Glass 2: N/A

Resin System: Primary: Epoxy

Flame retardant mechanism:

Fillers:

ID Reference:

Secondary 1: Multifunctional Epoxy Secondary 2: N/A Minimum UL94 Requirement: V1

Phosphorous Inorganic fillers

UL/ANSI: FR-4.1 Mil-S-13949: N/A

**ANSI:** FR-4.1 / 127 secondary 122/125/128

† 900 ppm max. Br or Cl and

Glass transition (TG): 110°C minimum 1500 ppm max. Br + Cl

Prepreg: R-1551 / R-1551W Laminate: R-1566 / R-1566W **Product name UL** - Designation R-1551 R-1566

1. Laminate		IPC Specification < 0, 5mm	IPC Specification ≥ 0, 5mm	Units	Typical Values < 0, 5mm	Typical Values ≥ 0, 5mm	Methode IPC-TM-650 (or as noted)
Physical Property							
Peel strength, minimum							
A: Low profile and very low profile copper foil, all copper foils > 18µm	18µm	0,7	0,7		-	-	2.4.8
B: Standard profile copper foil	35µm			N/mm			2.4.8.2 2.4.8.3
after thermal stress		0,8	1,05	1,5 1,4	1,6	2.4.0.3	
2. at 125°C		0,7	0,7		1,4	1,5	
3. after process solutions		0,55	0,8		1,5	1,6	
Moisture Absorptions, maximum		-	0,8	%	-	0,11	2.6.2.1
Flexural strength, minimum	A: Length direction	-	415	N/mm2	-	595	
	B: Cross direction	-	345		-	412	2.4.4
Flammability (Laminate and prepreg as laminated)		V1 min.	V1 min	Rating	V0	V0	UL 94
CTE (pre / post Tg )	1	_	_	ppm/°C		40/180	2.4.24
X	-			PP		13	
Y	-	_				15	
T260 (TMA)	copper removed			minutes	_	>120	2.4.24.1
T288 / T300 (TMA)	copper removed	_		minutes		22 / NA	2.4.24.1
Density	copper removed	_		g/cm3	2,0	2,0	2.4.24.1
Decomposition Temperature (5% loss)	-	_	-	°C	-	350	2.4.24.6
Electrical Property							
	A: 96 / 35 / 90	1,0 E+06	_		5 E+07		
Volume resistivity, minimum		1,0 2100		MOhm-	3 2 1 0 7	1,0 E+07	2.5.17.1
	B: after moisture resistance C: at elevated temp. E-24/125	405.00	1,0 E+06 1,0 E+03	cm	-		-
Surface resistivity, minimum		1,0 E+03	1,0 =+03				
	A: 96 / 35 / 90 B: after moisture resistance	1,0 E+04	1,0 E+04	MOhm	5,0 E+08	N/A	2.5.17.1
	C: at elevated temp. E-24/125	1,0 E+03	1,0 E+03	101011111	N/A N/A		
Dielectric breakdown, minimum	O. at clevated temp. E 24/120	1,0 2100	40	kV	-	> 50	2.5.6
Permittivity, maximum	at 1 MHz	5,4	5,4	-	N/A	4,95	2.0.0
( laminate and prepreg as laminated)	at 1 GHz	-	-		N/A	4,7	2.5.5.2/3/9
Loss tangent, maximum	at 1 MHz	0.035	0.035	_	0,014	0,014	
( laminate and prepreg as laminated)	at 1 GHz	-	-	_	0,011	0,011	2.5.5.2/3/9
Arc resistance, minimum		60	60	sec	NI	NI	2.5.1
Electrical strength, minimum / laminate and prepreg as laminated		30	-	kV/mm	49	-	2.5.6.2
CTI (comparative tracking index)		-	-	V	-	500	ASTM D3638
CAF resistance	1	-	AABUS	pass/fail	-	pass	2.6.25
Thermal Property							
Thermal stress 10 sec at 288°C, minimum	A: unetched	Pass	Pass	Rating	Pass	Pass	2.4.13.1
	B: etched	Pass	Pass		Pass	Pass	
Tg by DSC (TMA / DMA)		110 min.	110min	°C	152,7	153(145/180)	2.4.25
Thermal conductivity	1	-	-	W/mK	-	0,62	Laser flash
Specific heat	1	-	-	J/kgK	-	950	DSC
2. Prepreg Property		IPC-Specification		Units	Typical Values		
Shelf life, minimum	A: Condition <20°C, rel. H. <50%	90		Days	60		
(from date of delivery)	B: Condition <5°C	180			180		AABUS
Volatile content, maximum	1	0,75		%	meets requirements		2.3.19
Prepreg parameters	1	,	-	-	AAB	SUS	AABUS

AABUS= As agreed between user and supplier Note:

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